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SPECIFICATION FOR LCM+CTP Module

MODULE No:	ET070WV24-KT
CUSTOMER:	

YOURITECH	INITIAL	DATE
PREPARED BY		
CHECKED BY		
APPROVED BY		

CUSTOMER	INITIAL	DATE
APPROVED BY		



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* Description

This is a color active matrix TFT (Thin Film Transistor) LCD (liquid crystal display) that uses amorphous silicon TFT as a switching device. This model is composed of a Transmissive type TFT-LCD Panel, driver circuit, back-light unit. The resolution of a 7.0" TFT-LCD contains 800X480 pixels, and can display up to 65K/262K/16.7M colors.

* Features

General Information Items	Specification	Unit	Note
	Main Panel		
Display area(AA)	152.40(H) *91.44(V) (7.0inch)	mm	-
Driver element	TFT active matrix	-	-
Display colors	262K/16.7M	colors	-
Number of pixels	800(RGB)*480	dots	-
TFT Pixel arrangement	RGB vertical stripe	-	-
Pixel pitch	0.1905(H) x 0.1905 (V)	mm	-
Viewing angle	ALL	o'clock	-
TFT Controller IC	SC5004/SC5005	-	-
LCM Interface	6/8 BIT LVDS	-	-
Operating temperature	-30~+85	°C	-
Storage temperature	-40~+90	°C	-
Module bonding technology	Use Tape bonding between LCM and CTP	-	-

* CTP Features

General Information Items	Specification	Unit	Note
	Main Panel		
Resolution	800(H)*480(V)	-	
Structure	G+G	-	
Controller IC	GT9271	-	
Interface	I2C	-	
Slave Address	0x5D(7bit) or 0x14(7bit)	-	
Touch mode	Ten points	-	-
Logic level	1.8 or 3.3	V	Set by VDDIO

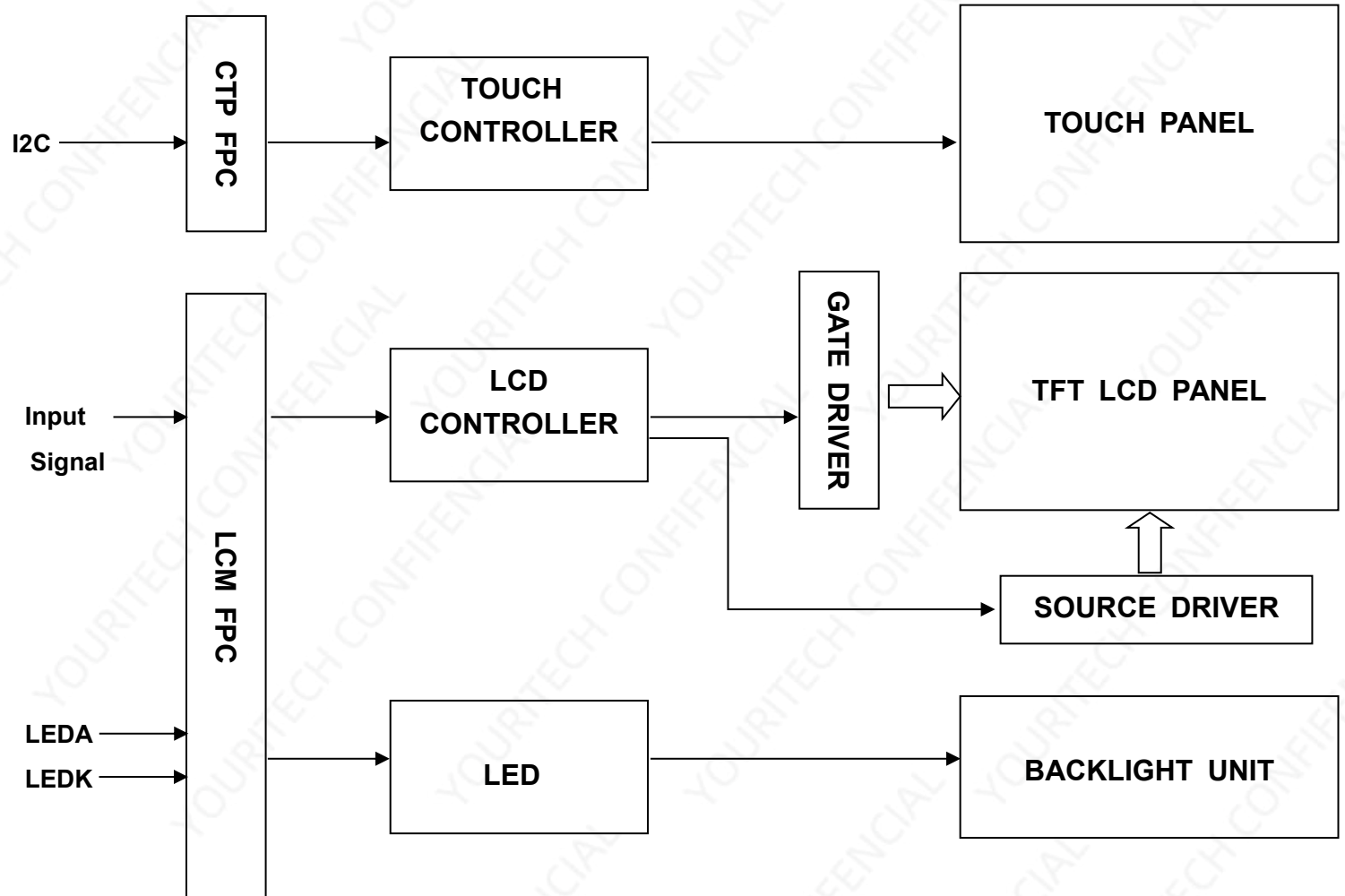


* Mechanical Information

Item		Min.	Typ.	Max.	Unit	Note
Module size	Horizontal(H)		165.40		mm	-
	Vertical(V)		104.59		mm	-
	Depth(D)		7.73		mm	-
Weight			TBD		g	-



1. Block Diagram



3. Input terminal Pin Assignment

3.1 TFT

NO.	SYMBOL	DISCRIPTION	I/O
1	NC	No connection.	
2	VDD	Supply voltage(3.3V).	P
3	VDD	Supply voltage(3.3V).	P
4	NC	No connection.	
5	RESET	Reset pin. The chip is in reset state when RESETB=0.	I
6	STBYB	Standby mode setting pin. The chip is in standby mode when S TBYB=0.	I
7	GND	Ground.	P
8	RXIN0-	- LVDS differential data input	I
9	RXIN0+	+ LVDS differential data input	I
10	GND	Ground.	P
11	RXIN1-	- LVDS differential data input	I
12	RXIN1+	+ LVDS differential data input	I
13	GND	Ground.	P
14	RXIN2-	- LVDS differential data input	I
15	RXIN2+	+ LVDS differential data input	I
16	GND	Ground.	P
17	RXCLKIN-	- LVDS differential clock input	I
18	RXCLKIN+	+ LVDS differential clock input	I
19	GND	Ground.	P
20	RXIN3-	- LVDS differential data input	I
21	RXIN3+	+ LVDS differential data input	I
22	GND	Ground.	P
23	NC	No connection.	
24	NC	No connection.	



25	GND	Ground.	P
26	NC	No connection.	
27	NC	No connection.	
28	SLEB	Input data format selection. SLEB=0, 8-BIT SLEB=1, 6-BIT	I
29	NC	No connection.	
30	GND	Ground.	I
31	LED-	LED Cathode	P
32	LED-	LED Cathode	P
33	L/R	Horizontal shift direction (source output) selection(NOTE1)	I
34	U/D	Vertical shift direction (gate output) selection(NOTE1)	I
35	XR(NC)	No connection.	
36	YD(NC)	No connection.	
37	XL(NC)	No connection.	
38	YU(NC)	No connection.	
39	LED+	LED Anode	P
40	LED+	LED Anode	P

NOTE1

L/R	1	Set left to right scan direction
L/R	0	Set right to left scan direction.
U/D	0	Set top to bottom scan direction
U/D	1	Set bottom to top scan direction



3.2 CTP

NO.	SYMBOL	DISCRIPTION	I/O
1	GND	Ground.	P
2	NC	--	--
3	VDD	Supply voltage.	P
4	SCL	I2C clock input.	I
5	SDA	I2C data input and output	I/O
6	INT	External interrupt to the host.	I
7	RST	External Reset, Low is active.	I
8	GND	Ground.	P



4. LCD Optical Characteristics

4.1 Optical specification

Item		Symbol	Condition	Min.	Typ.	Max.	Unit.	Note
Contrast Ratio		CR	$\Theta=0$	--	1000	--		2
Response time	Rising	T_R+T_F	Normal viewing angle	--	35	40	msec	3
	Falling			--				
Color gamut		S(%)		--	70	--	%	
Color Filter Chromaticity	White	W_X		-0.04	0.307	+0.04		
		W_Y			0.346			
	Red	R_X			0.639			
		R_Y			0.338			
	Green	G_X			0.327			
		G_Y			0.578			
	Blue	B_X			0.143			
		B_Y			0.067			
Viewing angle	Hor.	Θ_L	CR>10	--	85	--		
		Θ_R		--	85	--		
	Ver.	Θ_U		--	85	--		
		Θ_D		--	85	--		
Option View Direction		ALL						

*The data comes from the LCD specification.

Measuring Condition

Measuring surrounding : dark room

Ambient temperature : $25\pm 2^\circ\text{C}$

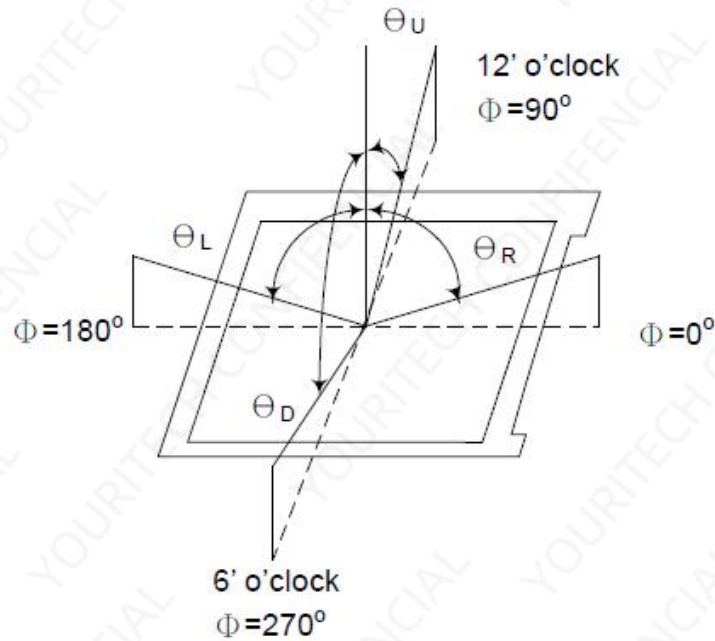
15min. warm-up time.

Measuring Equipment

FPM520 of Westar Display technologies, INC., which utilized SR-3 for Chromaticity and BM-5A for other optical characteristics.



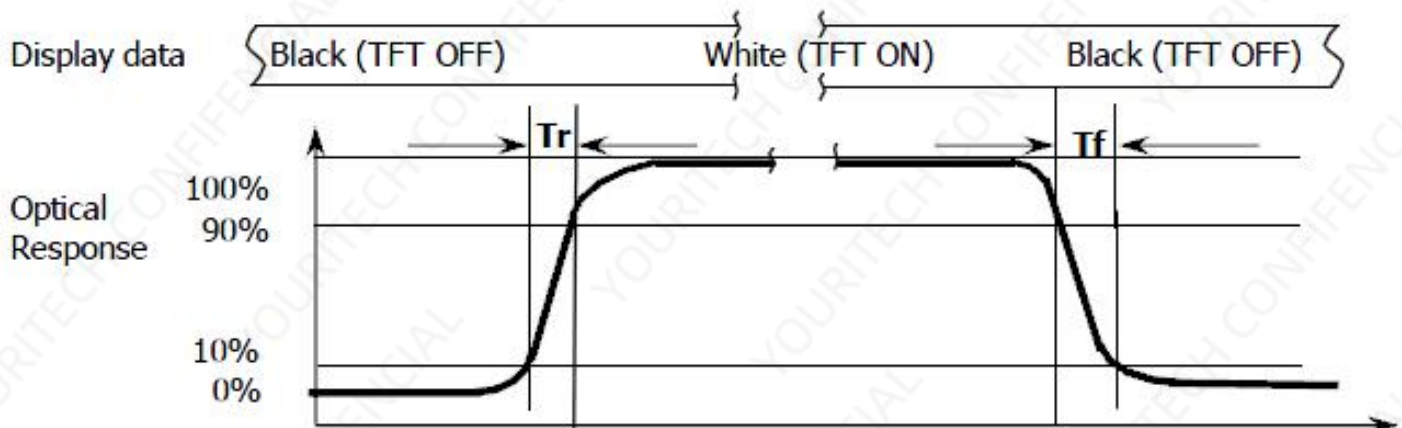
Note (1): Definition of Viewing Angle :



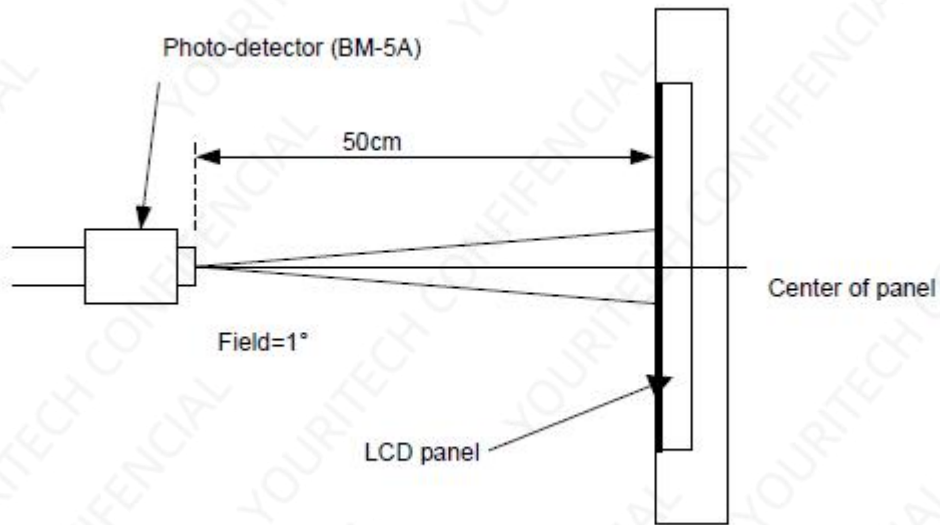
Note (2): Definition of Contrast Ratio(CR) :measured at the center point of panel

$$CR = \frac{\text{Luminance with all pixels white}}{\text{Luminance with all pixels black}}$$

Note (3): Response Time



Note (4): Definition of optical measurement setup



5. Electrical Characteristics

5.1 Absolute Maximum Rating ($T_a=25$ VSS=0V)

Characteristics	Symbol	Min.	Max.	Unit
Digital Supply Voltage	VDD	-0.3	4.0	V
Operating temperature	T _{OP}	-30	+85	°C
Storage temperature	T _{ST}	-40	+90	°C

NOTE: If the absolute maximum rating of even is one of the above parameters is exceeded even momentarily, the quality of the product may be degraded. Absolute maximum ratings, therefore, specify the values exceeding which the product may be physically damaged. Be sure to use the product within the range of the absolute maximum ratings.

5.2 DC Electrical Characteristics

Characteristics	Symbol	Min.	Typ.	Max.	Unit	Note
Digital Supply Voltage	VDD	3.0	3.3	3.6	V	
Digital Supply current	IDD	--	190	--	mA	
Level input voltage	V _{IH}	0.7V _{DD}		VDD	V	
	V _{IL}	GND		0.3V _{DD}	V	
Level output voltage	V _{OH}	0.8VDD		VDD	V	
	V _{OL}	GND		0.2VDD	V	



5.3 LED Backlight Characteristics

The back-light system is edge-lighting type with 60 chips White LED

Item	Symbol	Min.	Typ.	Max.	Unit	Note
Forward Current	I_F	180	200	--	mA	
Forward Voltage	V_F	--	19.2	--	V	
LCM Luminance	L_V	900	1000	--	cd/m2	
LED life time	Hr	50000	--	--	Hour	Note1,2
Uniformity	AVg	80	--	--	%	Note3

Note (1) LED life time (Hr) can be defined as the time in which it continues to operate under the condition:

$T_a=25\pm3\text{ }^{\circ}\text{C}$, typical IL value indicated in the above table until the brightness becomes less than 50%.

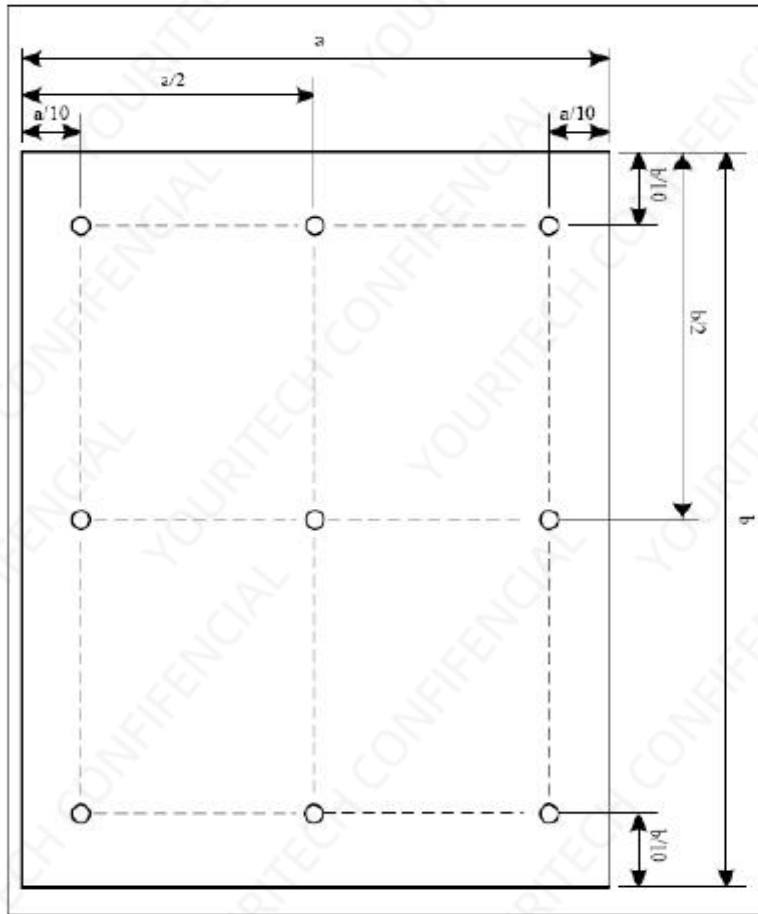
Note (2) The “LED life time” is defined as the module brightness decrease to 50% original brightness at $T_a=25^{\circ}\text{C}$ and $I_L=200\text{mA}$. The LED lifetime could be decreased if operating I_L is larger than 200mA. The constant current driving method is suggested.



BL CIRCUIT DIAGRAM



NOTE 3: Luminance Uniformity of these 9 points is defined as below:



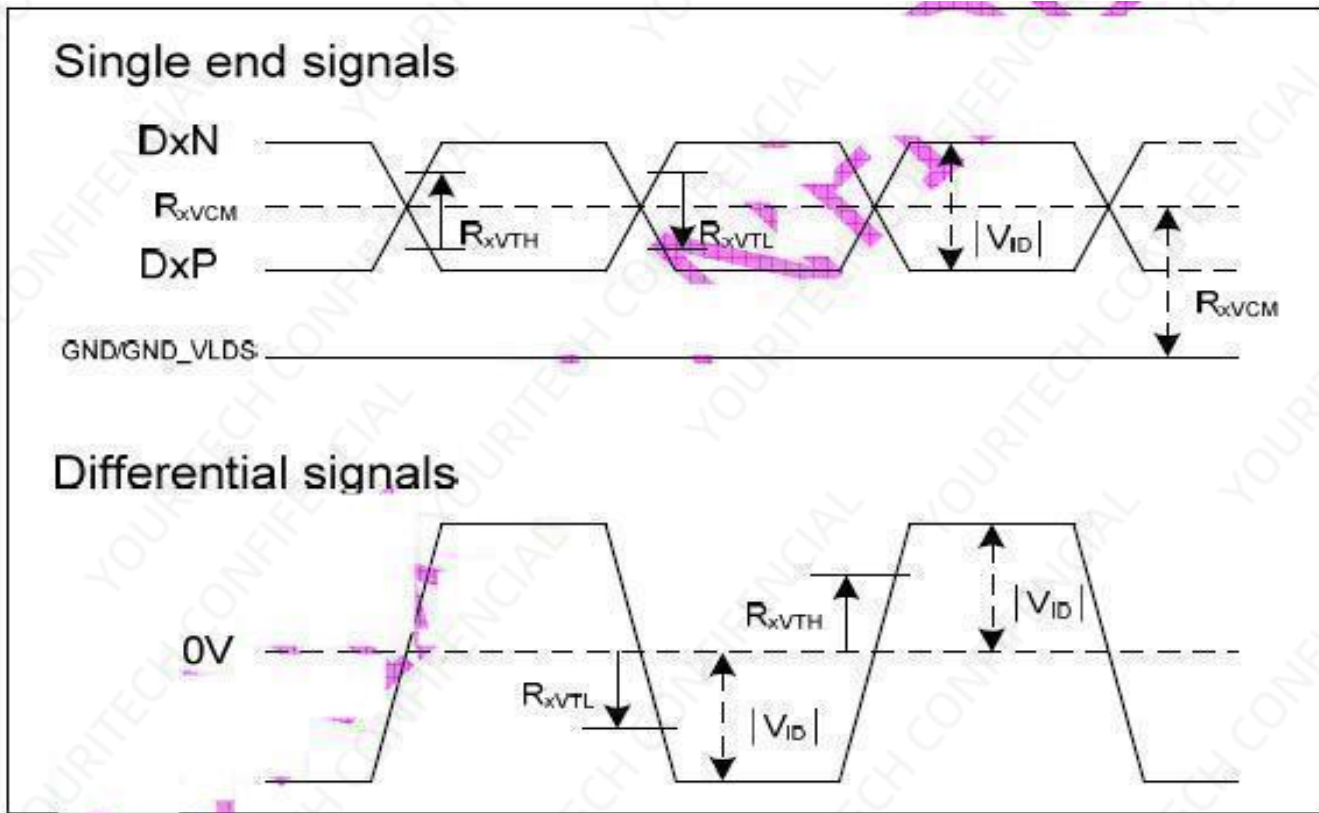
$$\text{Uniformity} = \frac{\text{minimum luminance in 9 points (1-9)}}{\text{maximum luminance in 9 points (1-9)}}$$

$$\text{Luminance} = \frac{\text{Total Luminance of 9 points}}{9}$$



6. AC Characteristic

6.1 LVDS receiver characteristic

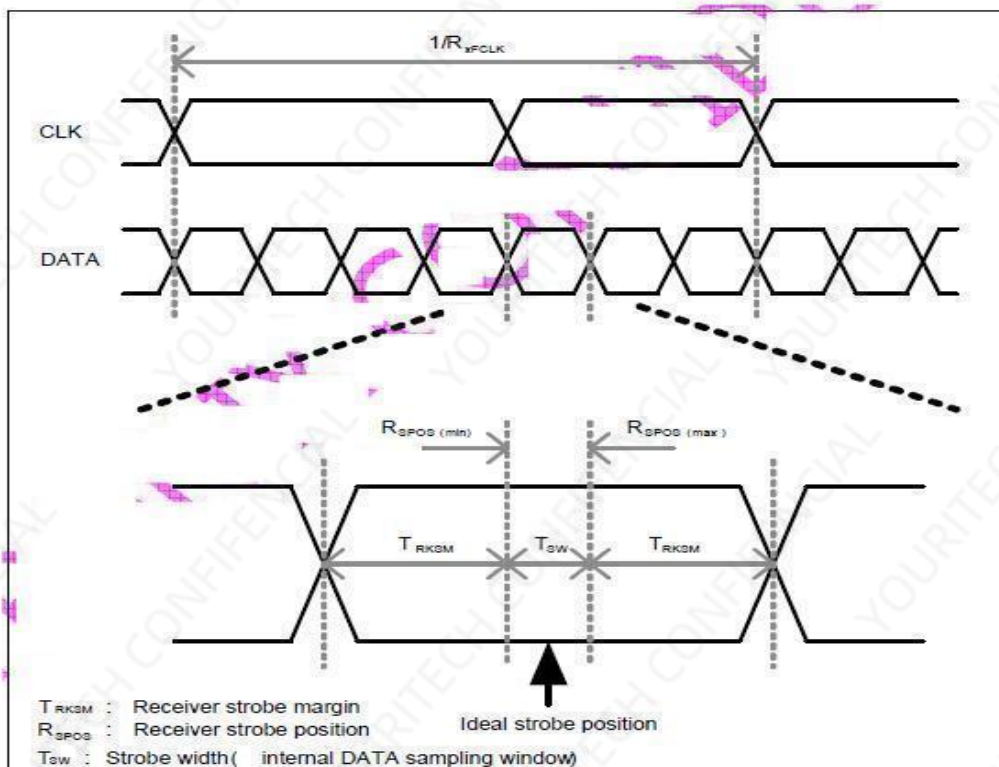
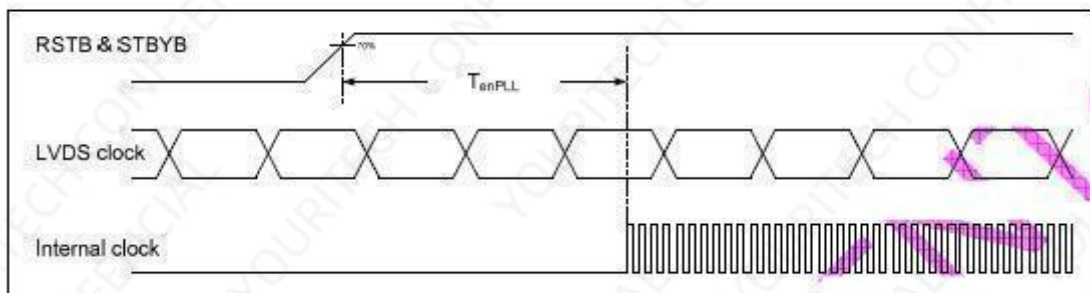
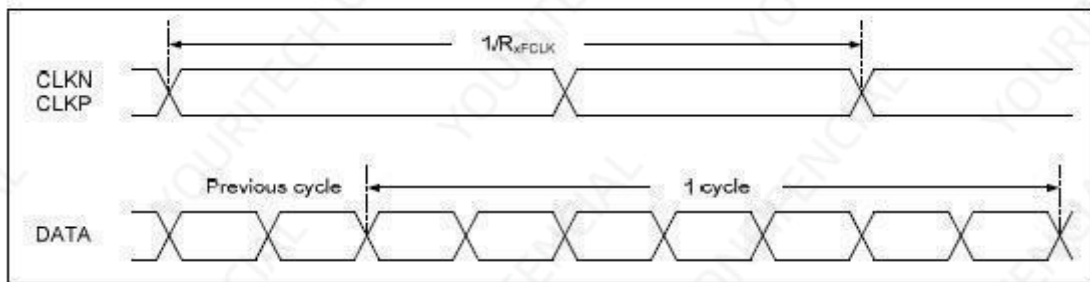


LVDS AC characteristic (VDD=VDD_LVDS=3.0~3.6V, GND=GND_LVDS=0V, TA=-20~85°C)

Parameter	Symbol	Min	Typ.	Max.	Unit	Conditions
Clock Frequency	R_{xFCLK}	20		80	MHz	
Input data skew margin	T_{RSKM}	400			ps	$ V_{ID} = 400mV, R_{xVCM}=1.2V$ $R_{xFCLK}=80MHz$
Clock high time	T_{LVCH}		$4/(7 \times R_{xFCLK})$		ns	
Clock low time	T_{LVCL}		$3/(7 \times R_{xFCLK})$		ns	
PLL wake-up time	T_{enPLL}			150	us	

Parameter	Symbol	Min	Typ.	Max.	Unit	Conditions
Differential input high threshold voltage	R_{xVTH}			0.1	V	$R_{xVCM} = 1.2V$
Differential input low threshold voltage	R_{xVTL}	-0.1			V	
Input voltage range (singled-end)	R_{xVIN}	0		VDD-1.0	V	
Differential input common mode voltage	R_{xVCM}	$ V_{ID} /2$		$2.4 - V_{ID} /2$	V	
Differential input voltage	$ V_{ID} $	0.2		0.6	V	
Differential input leakage current	$R_{V_{xIIZ}}$	-10		10	uA	
LVDS Digital Operating Current	I_{VDD_LVDS}	-	10	15	mA	$F_{CLK}=65\text{ MHz}$, $V_{DD_LVDS}=3.3V$ Data pattern=55/H → AA/H (loop)
LVDS Digital Stand-by Current	I_{STBD_LVDS}	-	10	50	uA	$RSTB=0$ or $STBYB=0$ All functions are stopped CLKx & D0x connect to GND





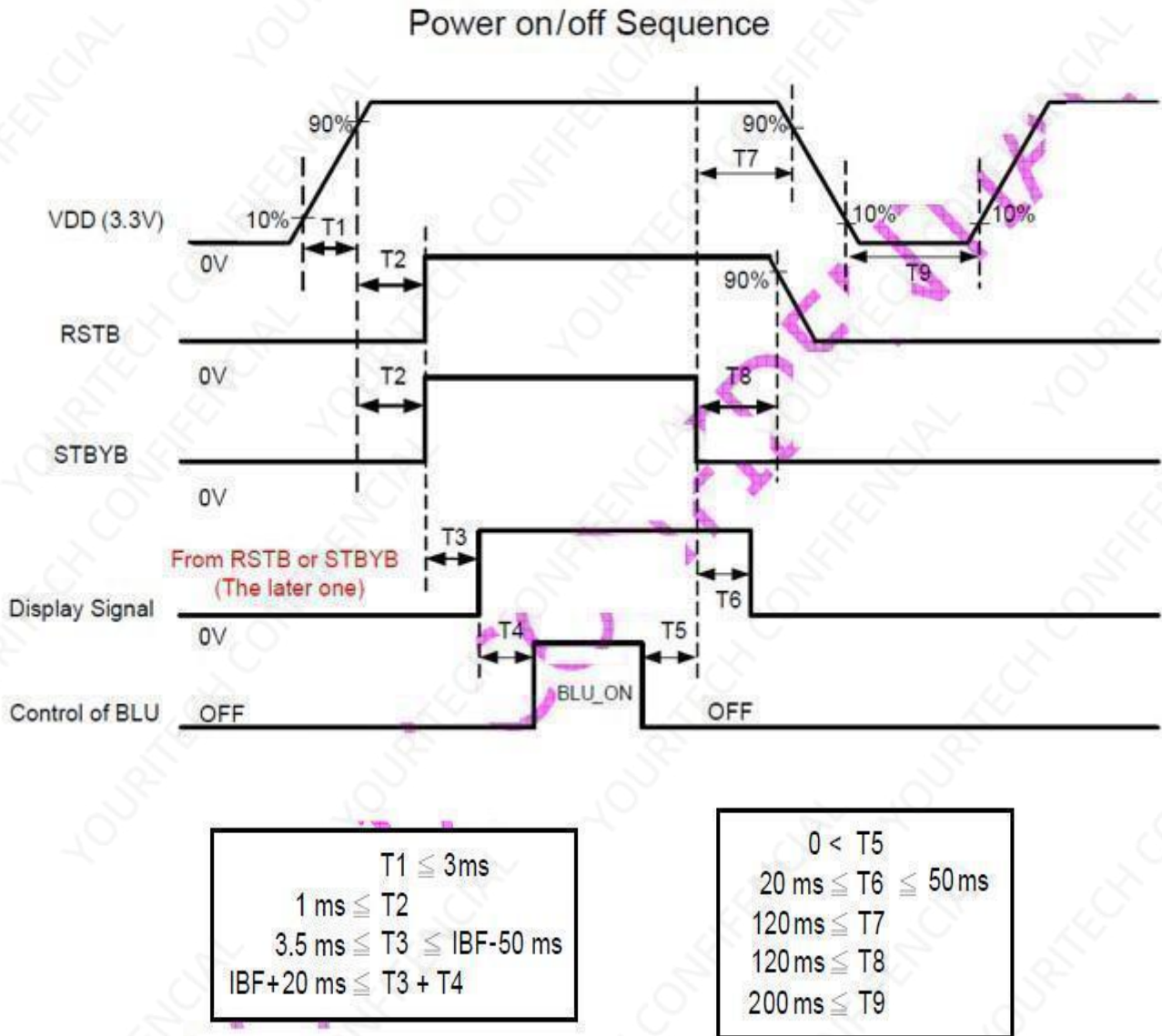
Spread Spectrum Clocking (SSC) tolerance of LVDS receiver

Parameter	Symbol	Min	Typ.	Max.	Unit	Conditions
Modulation frequency	SSCMF			100	kHz	
Modulation rate	SSCMR			+/-3	%	$R_{xCLK}=70MHz$



6.2 Power on/off Sequence

For TFT-LCD module, please follow below timings to prevent IC damage from abnormal power on or off sequence.

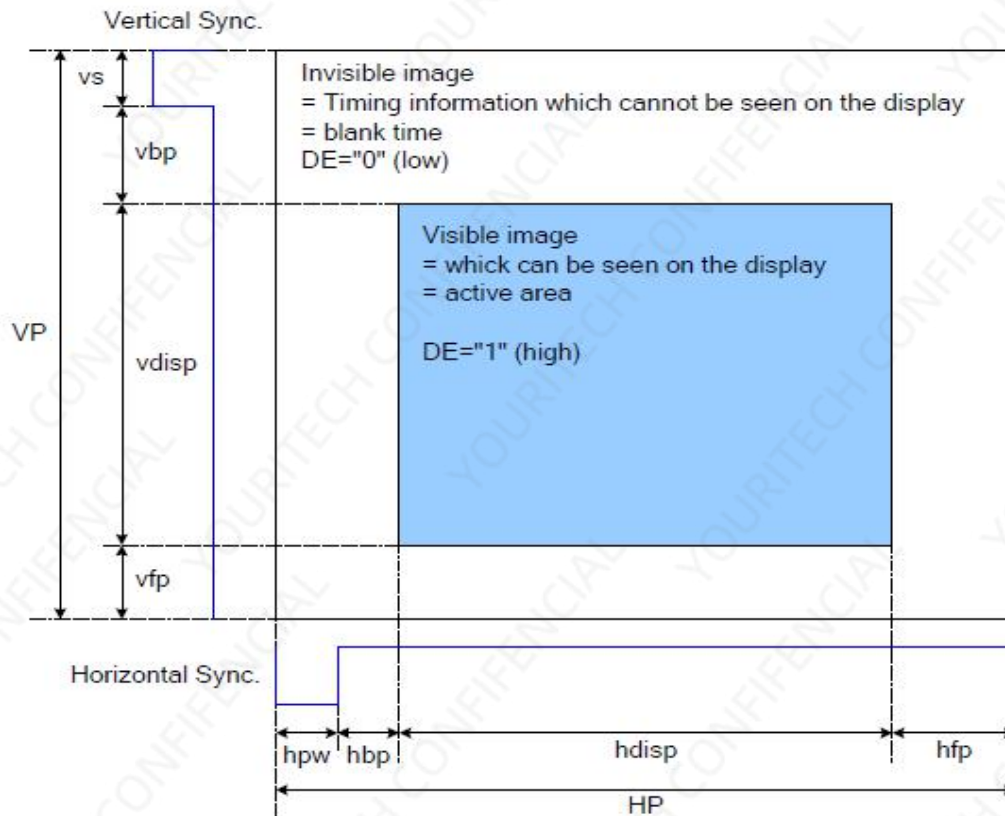


For continuously power off and on, please make sure the external VDD, VGH & VGL are discharged completely before you restart it.

Note that IBF is STSC5004's internal timing frames, selected by registers. Please refer to register list for detail.



6.3 Timing for LVDS mode



Parameter	Symbol	Min.	Typ.	Max.	Unit
DCLK frequency	FCLK	--	(28)	--	MHz
Horizontal display area	HDISP	--	800	--	Clock
Horizontal Sync. Width	hpw	1	4	--	Clock
Horizontal Sync. Back Porch	hbp	1	40	-	Clock
Horizontal Sync. Front Porch	hfp	1	90	--	Clock
Vertical display area	VDISP	--	480	--	Line
Vertical Sync. Width	vs	1	4	--	Line
Vertical Sync. Back Porch	vbp	1	8	--	Line
Vertical Sync. Front Porch	vfp	1	8	--	Line
Frame-Rate		--	60	--	Hz



7. CTP Specification

7.1 Electrical Characteristics

7.1.1 Absolute Maximum Rating

Item	Symbol	Min.	Max.	Unit	Note
Power Supply Voltage	VDD	2.66	3.47	V	1

NOTES:

- If used beyond the absolute maximum ratings, GT9271 may be permanently damaged. It is strongly recommended that the device be used within the electrical characteristics in normal operations. If exposed to the condition not within the electrical characteristics, it may affect the reliability of the device.

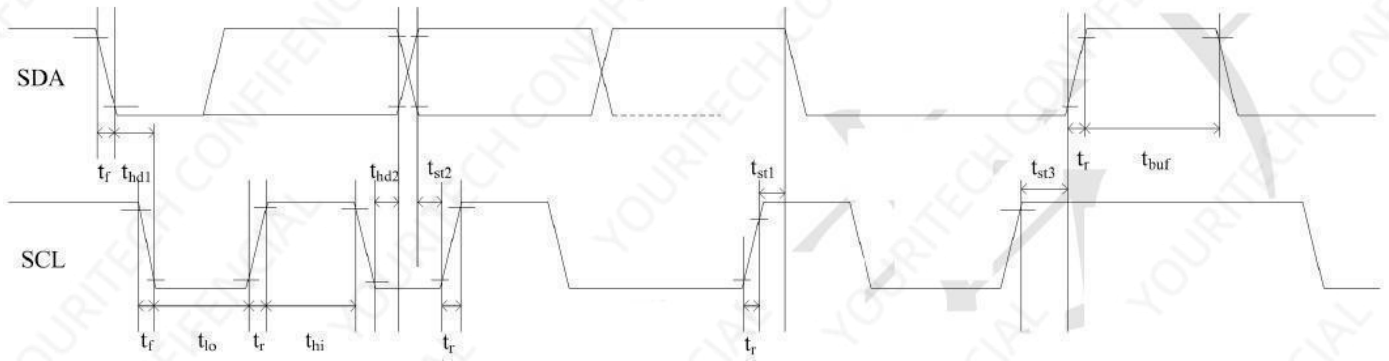
7.1.2 DC Electrical Characteristics (Ta=25°C)

Item	Symbol	Min.	Typ.	Max.	Unit	Note
Digital supply voltage	VDD	2.8	-	3.3	V	
Normal operation mode Current consumption	I _{opr}	-	13		mA	
Green mode Current consumption	I _{mon}	-	4.5	-	mA	
Sleep mode Current consumption	I _{slp}	70	-	120	uA	
Level input voltage	V _{IH}	0.75V _{DD}	-	V _{DD} +0.3	V	
	V _{IL}	-0.3	-	0.25V _{DD}	V	
Level output voltage	V _{OH}	0.85V _{DD}	-	-	V	
	V _{OL}	-	-	0.15V _{DD}	V	



7.2 AC Electrical Characteristics

GT9271 provides a standard I2C interface for SCL and SDA to communicate with the host. GT9271 always serves as slave device in the system with all communication being initialized by the host. It is strongly recommended that transmission rate be kept at or below 400Kbps. The I2C timing is shown below:



Test condition 1: 1.8V host interface voltage, 400Kbps transmission rate, 2K pull-up resistor

Parameter	Symbol	Min.	Max.	Unit
SCL low period	t_{lo}	1.3	-	us
SCL high period	t_{hi}	0.6	-	us
SCL setup time for Start condition	t_{st1}	0.6	-	us
SCL setup time for Stop condition	t_{st3}	0.6	-	us
SCL hold time for Start condition	t_{hd1}	0.6	-	us
SDA setup time	t_{st2}	0.1	-	us
SDA hold time	t_{hd2}	0	-	us

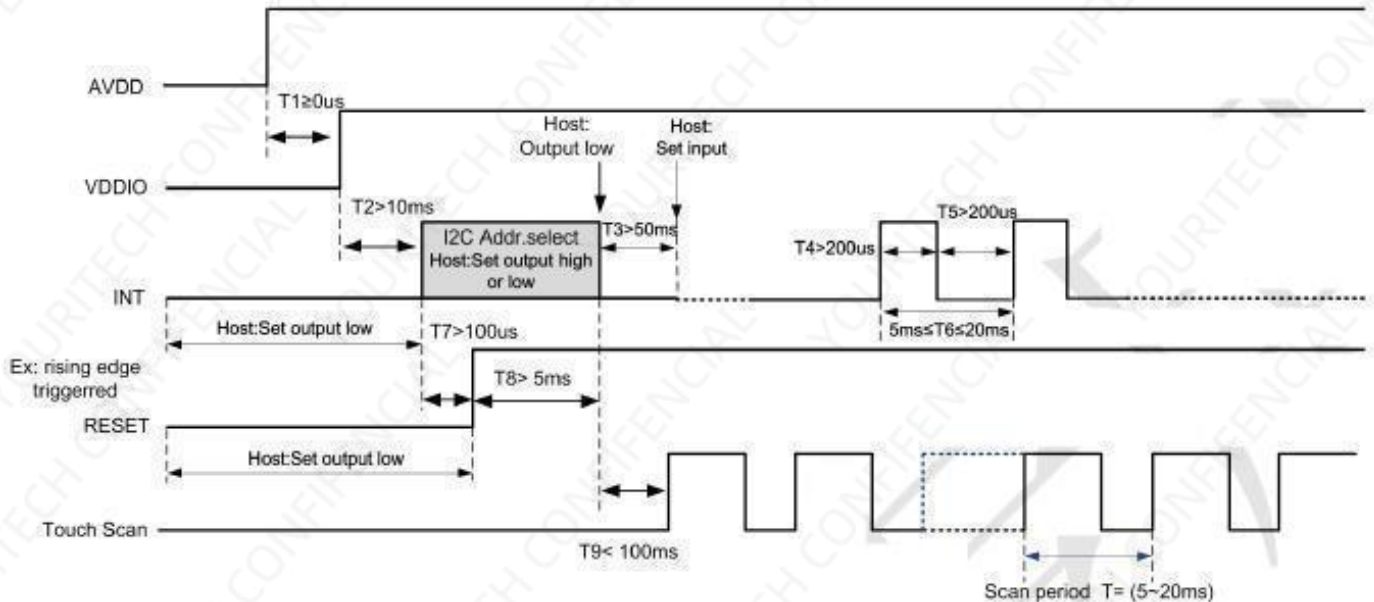
Test condition 2: 3.3V host interface voltage, 400Kbps transmission rate, 2K pull-up resistor

Parameter	Symbol	Min.	Max.	Unit
SCL low period	t_{lo}	1.3	-	us
SCL high period	t_{hi}	0.6	-	us
SCL setup time for Start condition	t_{st1}	0.6	-	us
SCL setup time for Stop condition	t_{st3}	0.6	-	us
SCL hold time for Start condition	t_{hd1}	0.6	-	us
SDA setup time	t_{st2}	0.1	-	us
SDA hold time	t_{hd2}	0	-	us

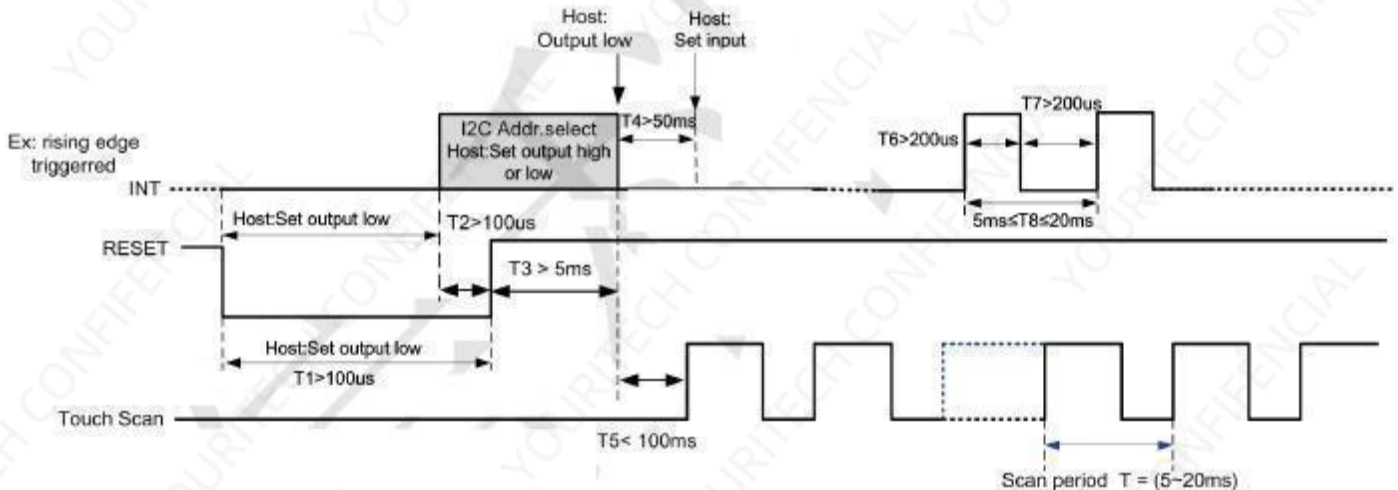


GT9271 supports two I2C slave addresses: 0xBA/0xBB and 0x28/0x29. The host can select the address by changing the status of Reset and INT pins during the power-on initialization phase. See the diagram below for configuration methods and timings:

Power-On Timing:

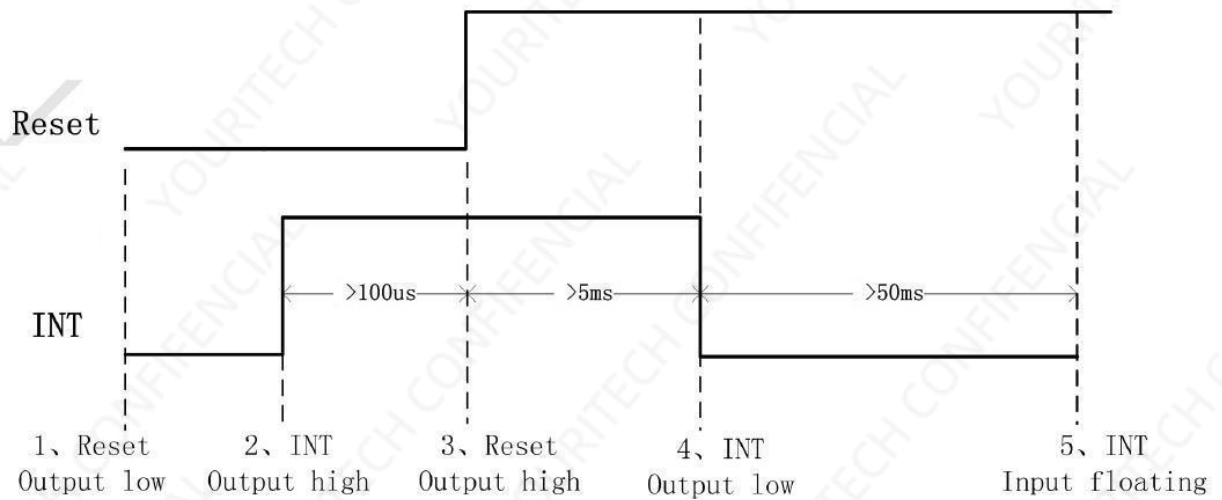


Timing for host resetting GT911:

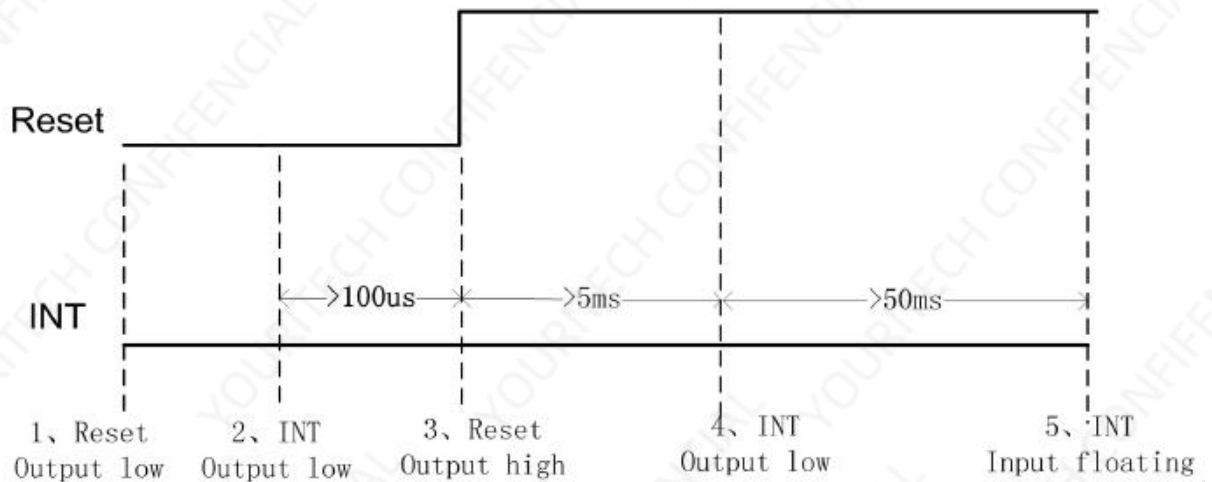


Timing for setting slave address to 0x28/0x29:





Timing for setting slave address to 0xBA/0xBB:



a) Data Transmission

(For example: slave address is 0xBA/0xBB)

Communication is always initiated by the host. Valid Start condition is signaled by pulling SDA from high to low when SCL line is high. Data flow or address is transmitted after the Start condition.

All slave devices connected to I²C bus should detect the 8-bit address issued after Start condition and send the correct ACK. After receiving matching address, GT9271 acknowledges by configuring SDA line as output port and pulling SDA line low during the ninth SCL cycle. When receiving unmatched address, namely, not 0xBA or 0xBB, GT9271 will stay in an idle state.



For data bytes on SDA, each of 9 serial bits will be sent on nine SCL cycles. Each data byte consists of 8 valid data bits and one ACK or NACK bit sent by the recipient. The data transmission is complete when SCL line is high.

When communication is completed, the host will issue the Stop condition which implies the transition of SDA line from low to high when SCL line is high.

b) Writing Data to GT9271

(For example: slave address is 0xBA/0xBB)



Timing for Write Operation

The diagram above displays the timing sequence of the host writing data onto GT9271. First, the host issues a Start condition. Then, the host sends 0xBA (address bits and R/W bit; R/W bit as 0 indicating Write operation) to the slave device.

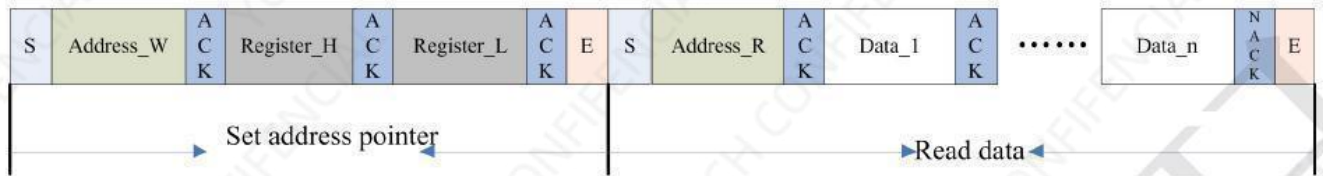
After receiving ACK, the host sends the 16-bit register address (where writing starts) and the data bytes (to be written onto the register).

The location of the register address pointer will automatically add 1 after every Write Operation. Therefore, when the host needs to perform Write Operations on a group of registers of continuous addresses, it is able to write continuously. The Write Operation is terminated when the host issues a Stop condition.



c) Reading Data from GT9271

(For example: slave address is 0xBA/0xBB)



Timing for Read Operation

The diagram above is the timing sequence of the host reading data from GT9271. First, the host issues a Start condition and sends 0xBA (address bits and R/W bit; R/W bit as 0 indicates Write operation) to the slave device.

After receiving ACK, the host sends the 16-bit register address (where reading starts) to the slave device. Then the host sets register addresses which need to be read.

Also after receiving ACK, the host issues the Start condition once again and sends 0xBB (Read Operation). After receiving ACK, the host starts to read data.

GT9271 also supports continuous Read Operation and, by default, reads data continuously. Whenever receiving a byte of data, the host sends an ACK signal indicating successful reception. After receiving the last byte of data, the host sends a NACK signal followed by a STOP condition which terminates communication.



8. LCD Module Out-Going Quality Level

8.1 VISUAL & FUNCTION INSPECTION STANDARD

8.1.1 Inspection conditions

Inspection performed under the following conditions is recommended.

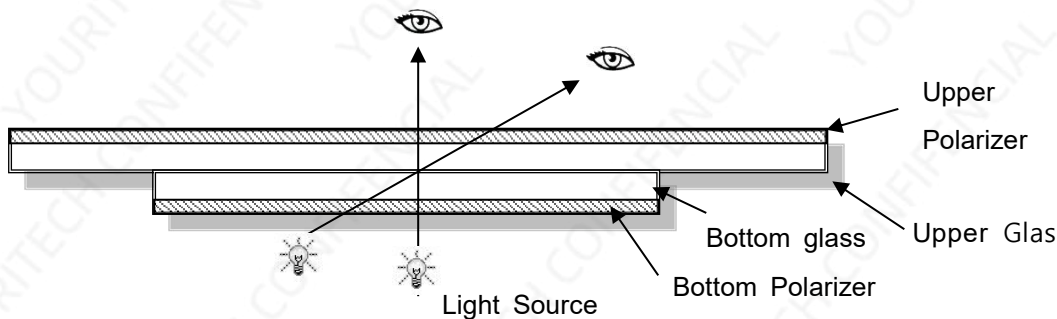
Temperature : $25\pm 5^{\circ}\text{C}$

Humidity : $65\%\pm 10\%\text{RH}$

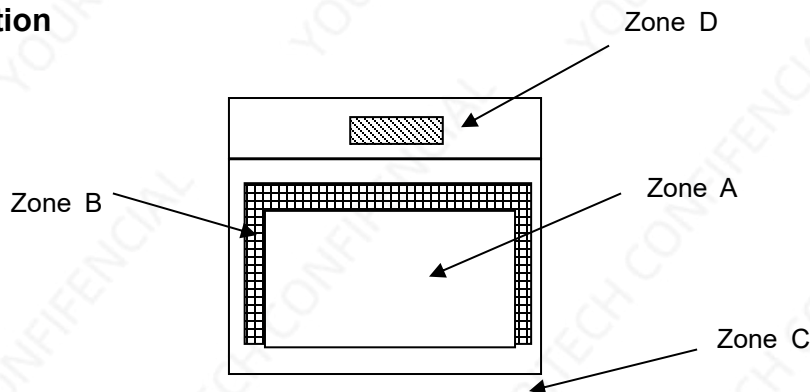
Viewing Angle : Normal viewing Angle.

Illumination: Single fluorescent lamp (300 to 700Lux)

Viewing distance:30-50cm



8.1.2 Definition



Zone A : Effective Viewing Area(Character or Digit can be seen)

Zone B : Viewing Area except Zone A

Zone C Cover (Zone A+Zone B) which can not be seen after assembly by customer .)

Zone D : IC Bonding Area

Note: As a general rule ,visual defects in Zone C can be ignored when it doesn't effect product function or appearance after assembly by customer



8.1.3 Sampling Plan

According to GB/T 2828-2003 ; , normal inspection, Class II

AQL:

Major defect	Minor defect
0.65	1.5

LCD: Liquid Crystal Display , LCM: Liquid Crystal Module, CTP: Capacitive Touch Panel

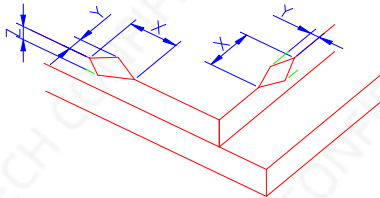
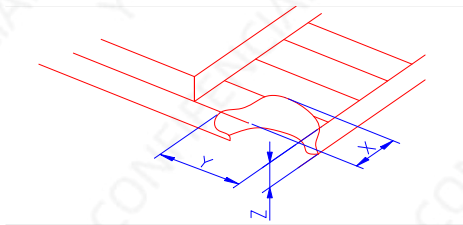
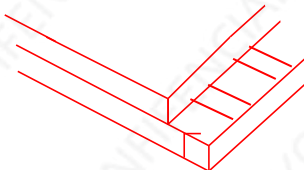
No	Items to be inspected	Criteria	Classification of defects
1	Functional defects	1) No display, Open or miss line 2) Display abnormally, Short 3) Backlight no lighting, abnormal lighting. etc	Major
2	Missing	Missing components and etc	
3	Outline dimension	Overall outline dimension beyond the drawing is not allowed, deformation and etc	
4	Color tone	Color unevenness, refer to limited sample	Minor
5	Spot/Line defect	Light dot, Dim spot, (Note1) Polarizer Air Bubble, Polarizer accidented spot and etc.	
6	Soldering appearance	Good soldering , Peeling off is not allowed and etc.	
7	LCD/Polarizer/CTP	Black/White spot/line, scratch, crack, etc.	

Note1: a) Light dot: Dots appear bright and unchanged in size in which LCD panel is displaying under black pattern.

b) Dim dot: Dots appear dark and unchanged in size in which LCD panel is displaying under pure red, green, blue picture.



8.1.4 Criteria (Visual)

Number	Items	Criteria(mm)						
1.0 LCD Crack/Broken NOTE: X: Length Y: Width Z: Height L: Length of IT O, T: Height of LCD	(1) The edge of LCD broken	 <table><tr><td>X</td><td>Y</td><td>Z</td></tr><tr><td>≤3.0mm</td><td><Inner border line of the seal</td><td>≤T</td></tr></table>	X	Y	Z	≤3.0mm	<Inner border line of the seal	≤T
	X	Y	Z					
	≤3.0mm	<Inner border line of the seal	≤T					
(2)LCD corner broken	 <table><tr><td>X</td><td>Y</td><td>Z</td></tr><tr><td>≤3.0mm</td><td>≤L</td><td>≤T</td></tr></table>	X	Y	Z	≤3.0mm	≤L	≤T	
X	Y	Z						
≤3.0mm	≤L	≤T						
(3) LCD crack	 Crack Not allowed							



2.0

Spot defect

$\Phi=(X+Y)/2$

① light dot (black/white spot , pinhole, stain, etc.)

Zone Size (mm)	Acceptable Qty		
	A	B	C
$\Phi \leq 0.15$	Ignore	Ignore	
$0.15 < \Phi \leq 0.25$	3(distance $\geq 10\text{mm}$)		
$0.25 < \Phi \leq 0.4$	2(distance $\geq 10\text{mm}$)		
$\Phi > 0.4$	0		

② Dim spot (light leakage、dent、dark spot, etc)

Zone Size (mm)	Acceptable Qty		
	A	B	C
$\Phi \leq 0.15$	Ignore	Ignore	
$0.15 < \Phi \leq 0.25$	3(distance $\geq 10\text{mm}$)		
$0.25 < \Phi \leq 0.4$	2(distance $\geq 10\text{mm}$)		
$\Phi > 0.4$	0		

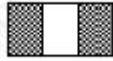
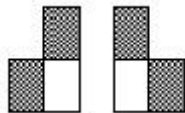
③ Polarizer accidented spot

Zone Size (mm)	Acceptable Qty			
	A	B	C	
$\Phi \leq 0.2$	Ignore		Ignore	
$0.2 < \Phi \leq 0.5$	2(distance $\geq 10\text{mm}$)			
$\Phi > 0.5$	0			

④Polarizer Bubble

Zone Size (mm)	Acceptable Qty			
	A	B	C	
$\Phi \leq 0.2$	Ignore		Ignore	
$0.2 < \Phi \leq 0.4$	3(distance $\geq 10\text{mm}$)			
$\Phi > 0.4$	0			



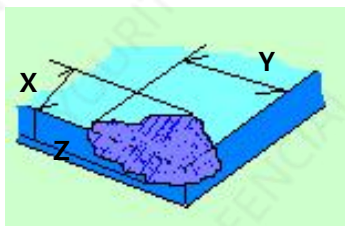
3.0	LCD Pixel defect	Pixel bad points																							
		<table> <tr> <th>Item</th><th>Zone A</th><th>Acceptable Qt</th></tr> <tr> <td rowspan="3">Bright dot</td><td>Random</td><td>$N \leq 2$</td></tr> <tr> <td>2 dots adjacent</td><td>$N \leq 0$</td></tr> <tr> <td>3 dots adjacent</td><td>$N \leq 0$</td></tr> <tr> <td rowspan="3">Dark dot</td><td>Random</td><td>$N \leq 2$</td></tr> <tr> <td>2 dots adjacent</td><td>$N \leq 0$</td></tr> <tr> <td>3 dots adjacent</td><td>$N \leq 0$</td></tr> <tr> <td>Distance</td><td> 1. Minimum Distance Between Bright dots. 2. Minimum Distance Between dark dots 3. Minimum Distance Between dark and bright dot. </td><td>5mm</td></tr> <tr> <td colspan="2">Total bright and dark dot</td><td>$N \leq 4$</td></tr> </table> Note: A) Bright dot: Dots appear bright and unchanged in size in which LCD panel is displaying under black pattern. B) Dark dot: Dots appear dark and unchanged in size in which LCD panel is displaying under pure red, green, blue picture. C) 2 dot adjacent = 1 pair = 2 dots Picture:   2 dot adjacent 2 dot adjacent (vertical)   2 dot adjacent 2 dot adjacent (slant)	Item	Zone A	Acceptable Qt	Bright dot	Random	$N \leq 2$	2 dots adjacent	$N \leq 0$	3 dots adjacent	$N \leq 0$	Dark dot	Random	$N \leq 2$	2 dots adjacent	$N \leq 0$	3 dots adjacent	$N \leq 0$	Distance	1. Minimum Distance Between Bright dots. 2. Minimum Distance Between dark dots 3. Minimum Distance Between dark and bright dot.	5mm	Total bright and dark dot		$N \leq 4$
Item	Zone A	Acceptable Qt																							
Bright dot	Random	$N \leq 2$																							
	2 dots adjacent	$N \leq 0$																							
	3 dots adjacent	$N \leq 0$																							
Dark dot	Random	$N \leq 2$																							
	2 dots adjacent	$N \leq 0$																							
	3 dots adjacent	$N \leq 0$																							
Distance	1. Minimum Distance Between Bright dots. 2. Minimum Distance Between dark dots 3. Minimum Distance Between dark and bright dot.	5mm																							
Total bright and dark dot		$N \leq 4$																							



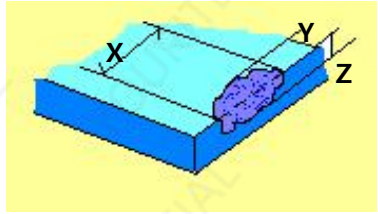
4.0	Line defect (LCD /Polarizer backlight black/white line, scratch, stain)	
		
	W: width, L : length	
	N : Count	

8.0	CTP Related	CTP Cover sensor ac cidented black/white spot				
			Size Φ (mm)	Acceptable Qty		
				A	B	C
			$\Phi \leq 0.1$	Ignore		Ignore
			$0.1 < \Phi \leq 0.2$			
			$0.20 < \Phi \leq 0.25$			
			$\Phi > 0.25$	0		



CTP Cover scratch	Width(mm)	Ignore (mm)	Acceptable Qty		
			A	B	C
	$\Phi \leq 0.05$	Ignore	Ignore		
	$0.05 < W \leq 0.06$	$L \leq 4.0$	$N \leq 3$		
	$0.06 < W \leq 0.08$	$L \leq 3.0$	$N \leq 2$		
	$0.08 < W$	Define as spot defect			
CTP Cover Pinhole/ Lack of ink	Zone Size (mm)		Acceptable Qty		
			C		
	$\Phi \leq 0.1$	Ignore			
	$0.1 < \Phi \leq 0.25$	3(distance $\geq 10\text{mm}$)			
	$0.25 < \Phi \leq 0.3$	2(distance $\geq 10\text{mm}$)			
	$\Phi > 0.3$	0			
CTP Bonding bubble/ accidented spot	Size $\Phi(\text{mm})$		Acceptable Qty		
			A	B	
	$\Phi \leq 0.1$	Ignore			
	$0.1 < \Phi \leq 0.2$	3(distance $\geq 10\text{mm}$)			
	$0.2 < \Phi \leq 0.25$	2(distance $\geq 10\text{mm}$)			
	$\Phi > 0.25$	0			
Assembly deflection	beyond the edge of backlight $\leq 0.2\text{mm}$				
CTP cover broken X : length Y : width Z : height	X	Y	Z		
	$X \leq 0.5\text{mm}$	$Y \leq 0.5\text{mm}$	$Z < \text{cover t hickness}$		
	* Circuitry broken is not allowed.				



		CTP cover broken	X	Y	Z	
			$X \leq 0.3\text{mm}$	$Y \leq 0.3\text{mm}$	$Z < \text{cover thickness}$	
		X : length	* Circuitry broken is not allowed.			
		Y : width				
		Z : height				

Criteria (functional items)

Number	Items	Criteria (mm)
1	No display	Not allowed
2	Missing segment	Not allowed
3	Short	Not allowed
4	Backlight no lighting	Not allowed
5	CTP no function	Not allowed



9. Reliability Test Result

Item	Condition	Inspection after test
High Temperature Operating	85°C, 96H	Inspection after 2~4hours storage at room temperature, the sample shall be free from defects: 1.Air bubble in the LCD; 2.Non-display; 3.Missing segments/line; 4.Glass crack; 5.Current IDD is twice higher than initial value.
Low Temperature Operating	-30°C, 96HR	
High Temperature Storage	90°C, 96HR	
Low Temperature Storage	-40°C, 96HR	
High Temperature & High Humidity Storage	+60°C, 90% RH ,96 hours.	
Thermal Shock (Non-operation)	-40°C, 30 min ↔ 90°C, 30 min, Change time: 5min 20CYC.	
ESD test	C=150pF, R=330, 5points/panel Air: ±8KV, 5times; Contact: ±6KV, 5 times; (Environment: 15°C~35°C, 30%~60%).	
Vibration (Non-operation)	Frequency range: 10~55Hz, Stroke: 1.5mm Sweep: 10Hz~55Hz~10Hz 2 hours for each direction of X.Y.Z. (6 hours for total) (Package condition).	
Box Drop Test	1 Corner 3 Edges 6 faces, 80cm (MEDIUM BOX)	

Remark:

- 1.The test samples should be applied to only one test item.
- 2.Sample size for each test item is 5~10pcs.
- 3.For Damp Proof Test, Pure water(Resistance > 10MΩ) should be used.
- 4.In case of malfunction defect caused by ESD damage, if it would be recovered to normal state after resetting, it would be judged as a good part.
- 5.Failure Judgment Criterion: Basic Specification, Electrical Characteristic, Mechanical Characteristic, Optical Characteristic.
6. The color fading mura of polarizing filter should not care.



10. Cautions and Handling Precautions

10.1 Handling and Operating the Module

(1) When the module is assembled, it should be attached to the system firmly.

Do not warp or twist the module during assembly work.

(2) Protect the module from physical shock or any force. In addition to damage, this may cause improper operation or damage to the module and back-light unit.

(3) Note that polarizer is very fragile and could be easily damaged. Do not press or scratch the surface.

(4) Do not allow drops of water or chemicals to remain on the display surface.

If you have the droplets for a long time, staining and discoloration may occur.

(5) If the surface of the polarizer is dirty, clean it using some absorbent cotton or soft cloth.

(6) The desirable cleaners are water, IPA (Isopropyl Alcohol) or Hexane.

Do not use ketene type materials (ex. Acetone), Ethyl alcohol, Toluene, Ethyl acid or Methyl chloride. It might permanent damage to the polarizer due to chemical reaction.

(7) If the liquid crystal material leaks from the panel, it should be kept away from the eyes or mouth. In case of contact with hands, legs, or clothes, it must be washed away thoroughly with soap.

(8) Protect the module from static; it may cause damage to the CMOS ICs.

(9) Use finger-stalls with soft gloves in order to keep display clean during the incoming inspection and assembly process.

(10) Do not disassemble the module.

(11) Protection film for polarizer on the module shall be slowly peeled off just before use so that the electrostatic charge can be minimized.

(12) Pins of I/F connector shall not be touched directly with bare hands.

(13) Do not connect, disconnect the module in the "Power ON" condition.

(14) Power supply should always be turned on/off by the item 6.1 Power On Sequence & 6.2 Power Off Sequence

10.2 Storage and Transportation.

(1) Do not leave the panel in high temperature, and high humidity for a long time.

It is highly recommended to store the module with temperature from 0 to 35 °C and relative humidity of less than 70%

(2) Do not store the TFT-LCD module in direct sunlight.

(3) The module shall be stored in a dark place. When storing the modules for a long time, be sure to adopt effective measures for protecting the modules from strong ultraviolet radiation, sunlight, or fluorescent light.

(4) It is recommended that the modules should be stored under a condition where no condensation is allowed. Formation of dewdrops may cause an abnormal operation or a failure of the module.

In particular, the greatest possible care should be taken to prevent any module from being operated where condensation has occurred inside.

(5) This panel has its circuitry FPC on the bottom side and should be handled carefully in order not to be stressed.



11. Packing

---TBD-----

